



2PD601ART

50 V, 100 mA NPN general-purpose transistor

Rev. 01 — 15 March 2007

Product data sheet

1. Product profile

1.1 General description

NPN general-purpose transistor in a small SOT23 (TO-236AB) Surface-Mounted Device (SMD) plastic package.

PNP complement: 2PB709ART.

1.2 Features

- General-purpose transistor
- Small SMD plastic package

1.3 Applications

- General-purpose switching and amplification

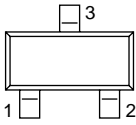
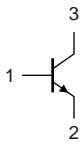
1.4 Quick reference data

Table 1. Quick reference data

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------|---------------------------|--|-----|-----|-----|------|
| V_{CE0} | collector-emitter voltage | open base | - | - | 50 | V |
| I_C | collector current | | - | - | 100 | mA |
| h_{FE} | DC current gain | $V_{CE} = 10\text{ V};$ $I_C = 2\text{ mA}$ | 210 | - | 340 | |

2. Pinning information

Table 2. Pinning

| Pin | Description | Simplified outline | Symbol |
|-----|-------------|---|---|
| 1 | base |  |  |
| 2 | emitter | | |
| 3 | collector | | |

sym021

3. Ordering information

Table 3. Ordering information

| Type number | Package | | |
|-------------|---------|--|---------|
| | Name | Description | Version |
| 2PD601ART | - | plastic surface-mounted package; 3 leads | SOT23 |

4. Marking

Table 4. Marking codes

| Type number | Marking code ^[1] |
|-------------|-----------------------------|
| 2PD601ART | C3* |

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

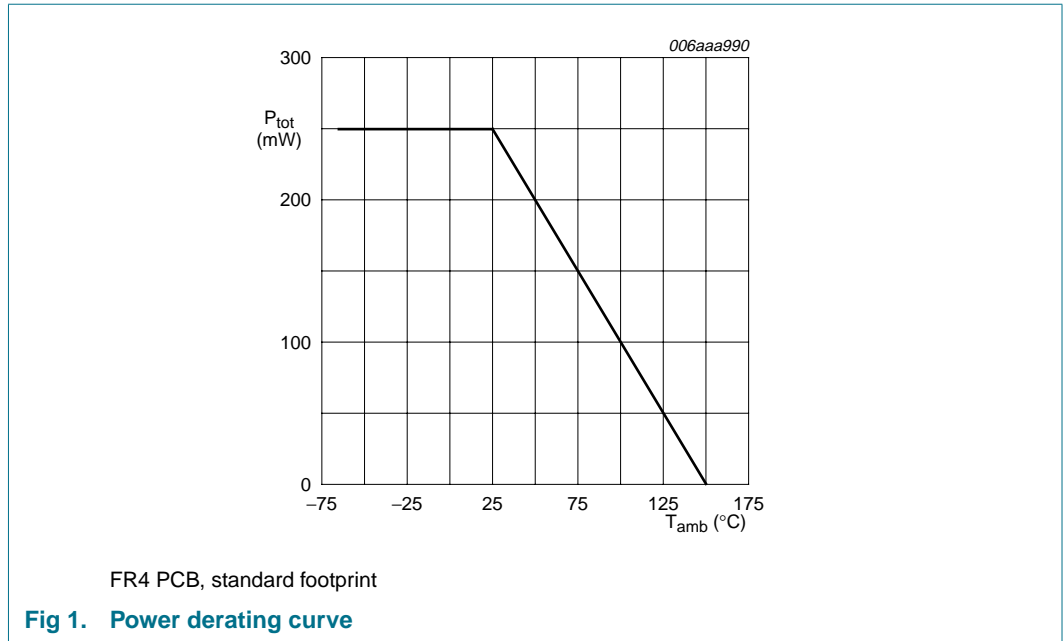
5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|---------------------------|----------------------------------|-------|------|------|
| V_{CBO} | collector-base voltage | open emitter | - | 60 | V |
| V_{CEO} | collector-emitter voltage | open base | - | 50 | V |
| V_{EBO} | emitter-base voltage | open collector | - | 6 | V |
| I_C | collector current | | - | 100 | mA |
| I_{CM} | peak collector current | single pulse; $t_p \leq 1$ ms | - | 200 | mA |
| I_{BM} | peak base current | single pulse; $t_p \leq 1$ ms | - | 100 | mA |
| P_{tot} | total power dissipation | $T_{amb} \leq 25$ °C | [1] - | 250 | mW |
| T_j | junction temperature | | - | 150 | °C |
| T_{amb} | ambient temperature | | -65 | +150 | °C |
| T_{stg} | storage temperature | | -65 | +150 | °C |

- [1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

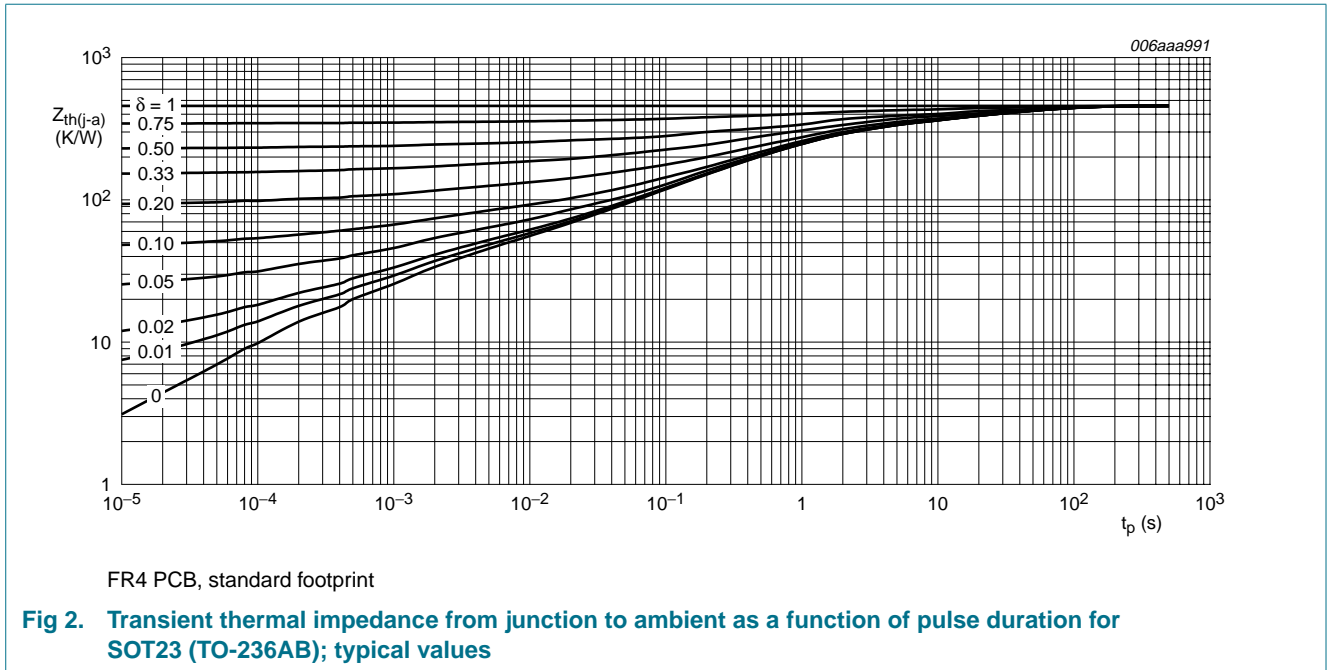


6. Thermal characteristics

Table 6. Thermal characteristics

| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-----------------------|--|-------------|-------|-----|-----|------|
| R _{th(j-a)} | thermal resistance from junction to ambient | in free air | [1] - | - | 500 | K/W |
| R _{th(j-sp)} | thermal resistance from junction to solder point | | - | - | 140 | K/W |

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.



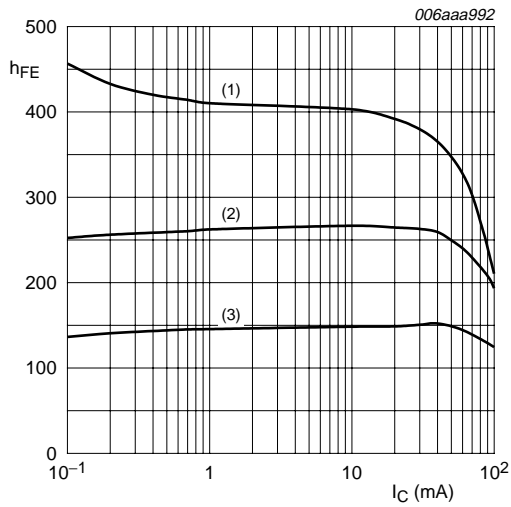
7. Characteristics

Table 7. Characteristics

$T_{amb} = 25^{\circ}C$ unless otherwise specified.

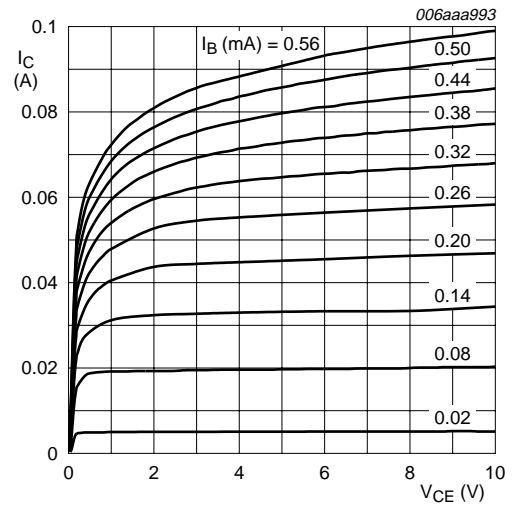
| Symbol | Parameter | Conditions | Min | Typ | Max | Unit |
|-------------|--------------------------------------|---|-----|-----|-----|---------|
| I_{CBO} | collector-base cut-off current | $V_{CB} = 60 V; I_E = 0 A$ | - | - | 10 | nA |
| | | $V_{CB} = 60 V; I_E = 0 A;$ $T_j = 150^{\circ}C$ | - | - | 5 | μA |
| I_{EBO} | emitter-base cut-off current | $V_{EB} = 5 V; I_C = 0 A$ | - | - | 10 | nA |
| h_{FE} | DC current gain | $V_{CE} = 2 V;$ $I_C = 100 mA$ | 90 | - | - | |
| | | $V_{CE} = 10 V;$ $I_C = 2 mA$ | 210 | - | 340 | |
| V_{CEsat} | collector-emitter saturation voltage | $I_C = 100 mA;$ $I_B = 10 mA$ | [1] | - | 250 | mV |
| f_T | transition frequency | $V_{CE} = 10 V;$ $I_C = 2 mA;$ $f = 100 MHz$ | 100 | - | - | MHz |
| C_c | collector capacitance | $V_{CB} = 10 V;$ $I_E = i_e = 0 A;$ $f = 1 MHz$ | - | - | 3 | pF |

[1] Pulse test: $t_p \leq 300 \mu s; \delta \leq 0.02$.



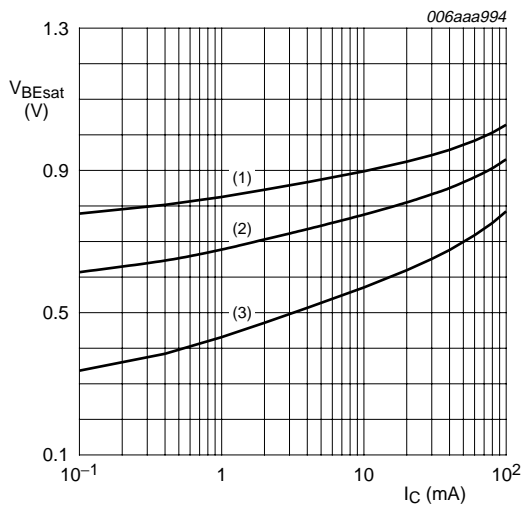
$V_{CE} = 10\text{ V}$
 (1) $T_{amb} = 150\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = -55\text{ }^\circ\text{C}$

Fig 3. DC current gain as a function of collector current; typical values



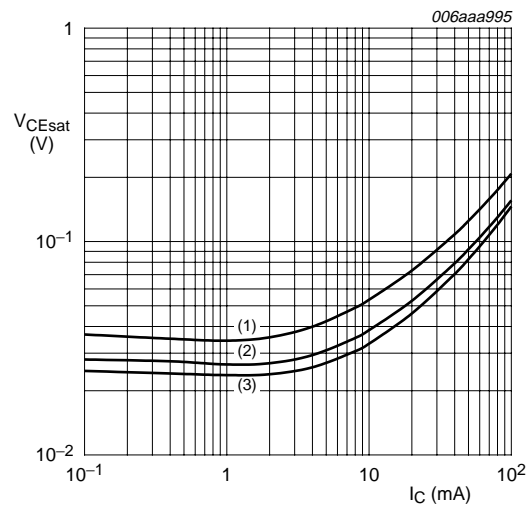
$T_{amb} = 25\text{ }^\circ\text{C}$

Fig 4. Collector current as a function of collector-emitter voltage; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = -55\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = 150\text{ }^\circ\text{C}$

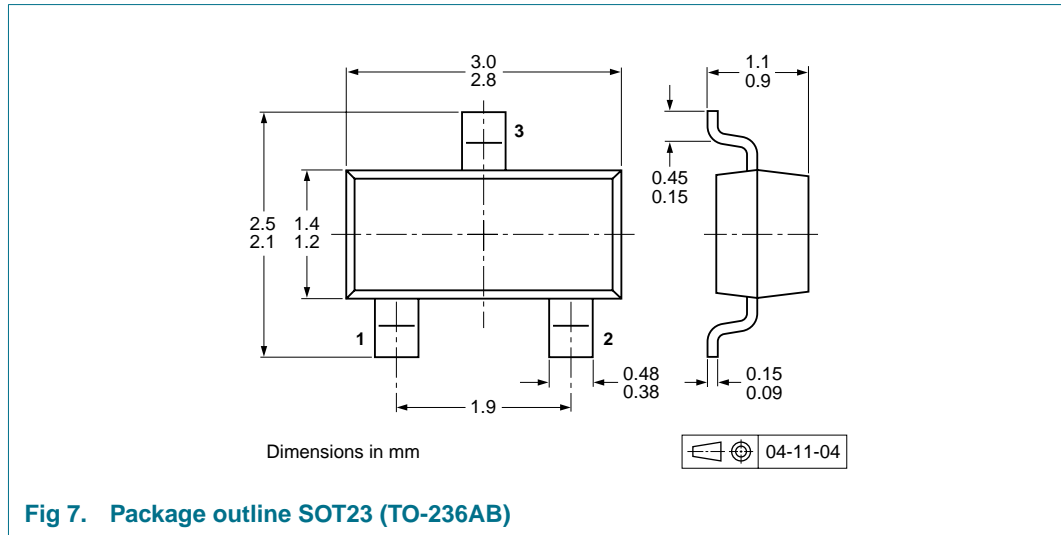
Fig 5. Base-emitter saturation voltage as a function of collector current; typical values



$I_C/I_B = 10$
 (1) $T_{amb} = 150\text{ }^\circ\text{C}$
 (2) $T_{amb} = 25\text{ }^\circ\text{C}$
 (3) $T_{amb} = -55\text{ }^\circ\text{C}$

Fig 6. Collector-emitter saturation voltage as a function of collector current; typical values

8. Package outline



9. Packing information

Table 8. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.^[1]

| Type number | Package | Description | Packing quantity | |
|-------------|---------|--------------------------------|------------------|-------|
| | | | 3000 | 10000 |
| 2PD601ART | SOT23 | 4 mm pitch, 8 mm tape and reel | -215 | -235 |

[1] For further information and the availability of packing methods, see [Section 13](#).

10. Soldering

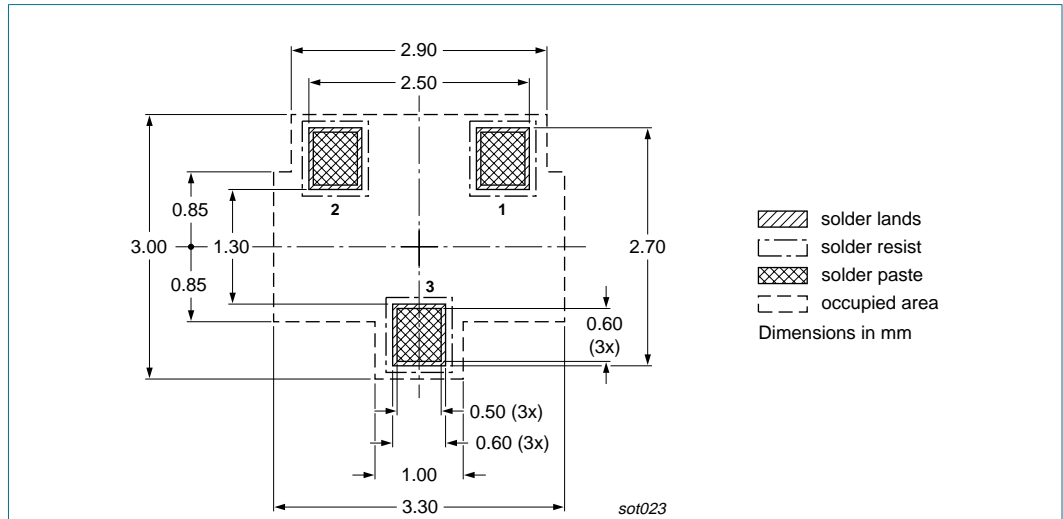


Fig 8. Reflow soldering footprint SOT23 (TO-236AB)

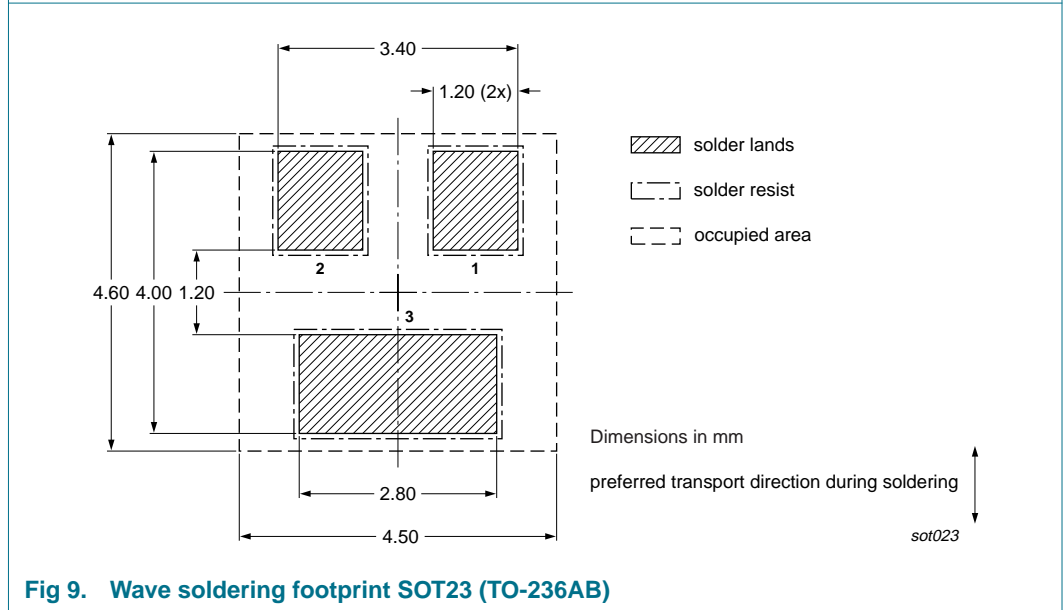


Fig 9. Wave soldering footprint SOT23 (TO-236AB)

11. Revision history

Table 9. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------|--------------|--------------------|---------------|------------|
| 2PD601ART_1 | 20070315 | Product data sheet | - | - |

12. Legal information

12.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
|-----------------------------------|-------------------------------|---|
| Objective [short] data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification | This document contains data from the preliminary specification. |
| Product [short] data sheet | Production | This document contains the product specification. |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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14. Contents

1 Product profile 1

1.1 General description 1

1.2 Features 1

1.3 Applications 1

1.4 Quick reference data 1

2 Pinning information 1

3 Ordering information 2

4 Marking 2

5 Limiting values 2

6 Thermal characteristics 3

7 Characteristics 4

8 Package outline 6

9 Packing information 6

10 Soldering 7

11 Revision history 8

12 Legal information 9

12.1 Data sheet status 9

12.2 Definitions 9

12.3 Disclaimers 9

12.4 Trademarks 9

13 Contact information 9

14 Contents 10

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